MOSFET – Dual, N-Channel with ESD Protection, Small Signal, SOT-563 60 V, 310 mA

Features

- Low R_{DS(on)} Improving System Efficiency
- Low Threshold Voltage
- ESD Protected Gate
- Small Footprint 1.6 x 1.6 mm
- These are Pb-Free Devices

Applications

- Load/Power Switches
- Driver Circuits: Relays, Lamps, Displays, Memories, etc.
- Battery Management/Battery Operated Systems
- Cell Phones, Digital Cameras, PDAs, Pagers, etc.

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted.)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	60	V
Gate-to-Source Voltage			V_{GS}	±20	V
Continuous Drain	Steady	$T_A = 25^{\circ}C$	I _D	294	mA
Current (Note 1)	State	T _A = 85°C		212	
Power Dissipation (Note 1)	Stea	dy State	P _D	250	mW
Continuous Drain	t≤5s	$T_A = 25^{\circ}C$	I _D	310	mA
Current (Note 1)	l≥os	T _A = 85°C		225	
Power Dissipation (Note 1)	t ≤ 5 s		P _D	280	mW
Pulsed Drain Current	t _p = 10 μs		I _{DM}	590	mA
Operating Junction and Storage Temperature			T _J , T _{STG}	–55 to 150	°C
Source Current (Body Diode)			IS	350	mA
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C
Gate-Source ESD Rating (HBM, Method 3015)		ESD	1800	V	

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	500	°C/W
Junction-to-Ambient – $t \le 5$ s (Note 1)		447	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

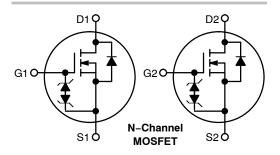
 Surface mounted on FR4 board using 1 in sq pad size (Cu. area = 1.127 in sq [1 oz] including traces).



ON Semiconductor®

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V _{(BR)DSS}	R _{DS(on)} MAX	I _D Max
60	1.6 Ω @ 10 V	310 mA
60	2.5 Ω @ 4.5 V	310 IIIA





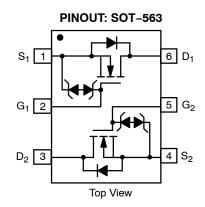


MARKING

S7 = Specific Device Code

M = Date Code

(Note: Microdot may be in either location)



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted.)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I_D = 250 μA		60	-	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	-		-	71	-	mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V	T _J = 25°C	-	-	1.0	μΑ
		$V_{DS} = 60 \text{ V}$	T _J = 125°C	-	-	500	1
		V _{GS} = 0 V	T _J = 25°C	-	-	100	nA
		$V_{DS} = 50 \text{ V}$	T _J = 85°C	-	-	100	1
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 V, V_{GS}$	= ±20 V	-	-	±10	μΑ
		$V_{DS} = 0 V, V_{GS}$	= ±10 V	-	-	450	nA
		$V_{DS} = 0 V, V_{GS}$	= ±5.0 V	ı	-	150	nA
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}$, $I_D = 250 \mu A$		1.0	-	2.5	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J	-		-	4.0	-	mV/°C
Drain-to-Source On Resistance	On Resistance $R_{DS(on)} = V_{GS} = 10 \text{ V}, I_D = 500 \text{ mA}$ $V_{GS} = 4.5 \text{ V}, I_D = 200 \text{ mA}$	= 500 mA	-	1.19	1.6	Ω	
		$V_{GS} = 4.5 \text{ V}, I_D = 200 \text{ mA}$		-	1.33	2.5	1
Forward Transconductance	9 _{FS}	V _{DS} = 5.0 V, I _D = 200 mA		-	80	-	S
CHARGES AND CAPACITANCES							
Input Capacitance	C _{ISS}	$V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz,}$ $V_{DS} = 20 \text{ V}$		-	24.5	_	pF
Output Capacitance	C _{OSS}			-	4.2	-	1
Reverse Transfer Capacitance	C _{RSS}			-	2.2	-	1
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = 4.5 \text{ V}, V_{DS} = 10 \text{ V};$ $I_D = 200 \text{ mA}$		-	0.7	-	nC
Threshold Gate Charge	Q _{G(TH)}			-	0.1	-	1
Gate-to-Source Charge	Q_{GS}			-	0.3	-	1
Gate-to-Drain Charge	Q_{GD}			ı	0.1	-	
SWITCHING CHARACTERISTICS (Note 4)							
Turn-On Delay Time	t _{d(ON)}	V_{GS} = 10 V, V_{DD} = 30 V, I_{D} = 200 mA, R_{G} = 10 Ω		-	12	-	ns
Rise Time	t _r			-	7.3	-	1
Turn-Off Delay Time	t _{d(OFF)}			-	63.7	-]
Fall Time	t _f				30.6	_	<u>l</u>
DRAIN-SOURCE DIODE CHARACTERISTIC	s						
Forward Diode Voltage	V	$V_{GS} = 0 \text{ V},$ $I_{S} = 200 \text{ mA}$ $T_{J} = 25^{\circ}\text{C}$ $T_{J} = 85^{\circ}\text{C}$		-	0.8	1.2	V
	V_{SD}			-	0.7	-]

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Surface–mounted on FR4 board using 1 in. sq. pad size (Cu. area = 1.127 in sq [1 oz] including traces).

3. Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.

4. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

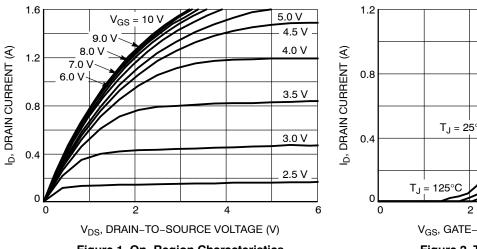


Figure 1. On-Region Characteristics

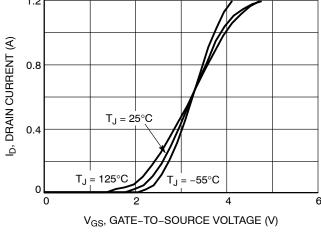


Figure 2. Transfer Characteristics

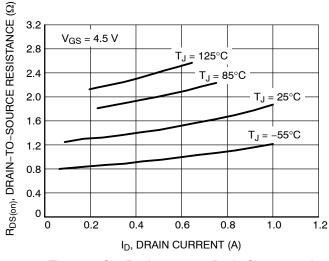


Figure 3. On-Resistance vs. Drain Current and **Temperature**

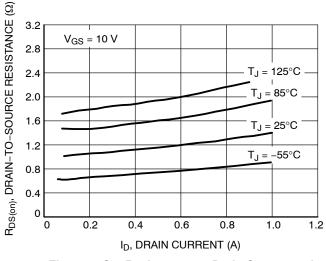


Figure 4. On-Resistance vs. Drain Current and **Temperature**

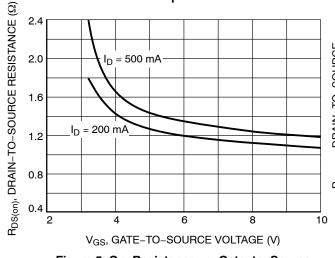


Figure 5. On-Resistance vs. Gate-to-Source Voltage

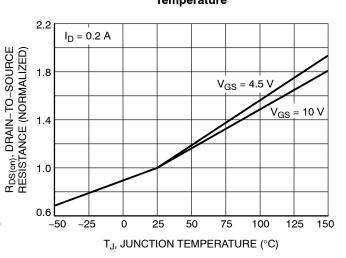


Figure 6. On-Resistance Variation with Temperature

TYPICAL CHARACTERISTICS

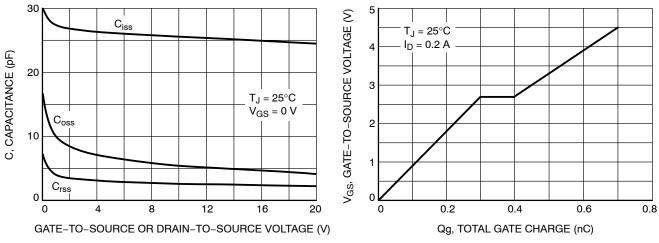


Figure 7. Capacitance Variation

Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

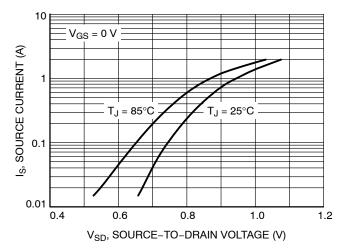


Figure 9. Diode Forward Voltage vs. Current

ORDERING INFORMATION

Device	Package	Shipping
NTZD5110NT1G	SOT-563 (Pb-Free)	4000 / Tape & Reel
NTZD5110NT5G	SOT-563 (Pb-Free)	8000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



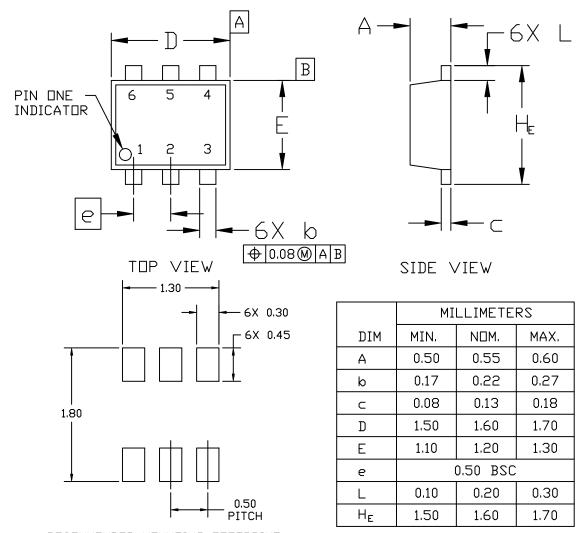


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NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.



RECOMMENDED MOUNTING FOOTPRINT*

For additional information on our Pb-Free strategy and soldering details, please download the IIN Semiconductor Soldering and Mounting Techniques Reference Manual, SILDERRM/D.

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STYLE 1: PIN 1. EMITTER 1 2. BASE 1 3. COLLECTOR 2 4. EMITTER 2 5. BASE 2 6. COLLECTOR 1	STYLE 2: PIN 1. EMITTER 1 2. EMITTER 2 3. BASE 2 4. COLLECTOR 2 5. BASE 1 6. COLLECTOR 1	STYLE 3: PIN 1. CATHODE 1 2. CATHODE 1 3. ANODE/ANODE 2 4. CATHODE 2 5. CATHODE 2 6. ANODE/ANODE 1
	STYLE 5: PIN 1. CATHODE 2. CATHODE 3. ANODE 4. ANODE 5. CATHODE 6. CATHODE	
	STYLE 8: PIN 1. DRAIN 2. DRAIN 3. GATE 4. SDURCE 5. DRAIN 6. DRAIN	
STYLE 10: PIN 1. CATHODE 1 2. N/C 3. CATHODE 2 4. ANODE 2 5. N/C 6. ANODE 1	STYLE 11: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	

GENERIC MARKING DIAGRAM*



XX = Specific Device Code

M = Month Code

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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